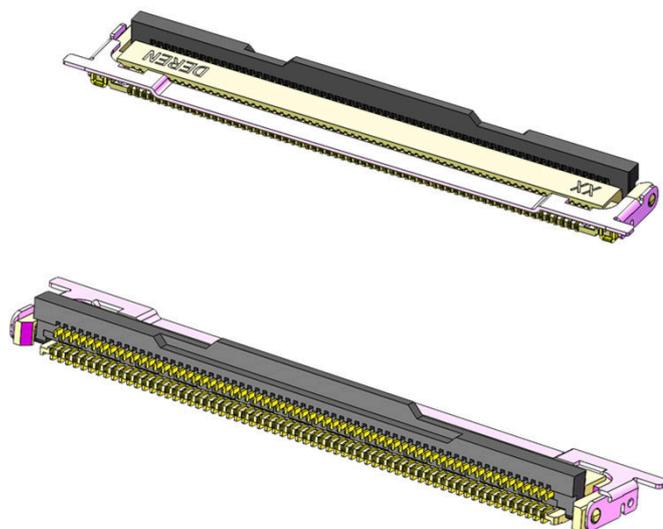




FFC/FPC is used in many different applications in desk top, mobile, as well as networking and communication equipment. Consequently, multiple variations of form factors and connectors will exist to suit the unique needs of these different applications. FFC/FPC connector system meets industrial specification requiring higher bandwidth applications from 2.5GT/s to 32GT/s. The optimized connector design delivers better impedance continuities to improved the insertion loss and return loss. The simple, functional design (without ground pins shortcut in the connector) contributes to a very cost-effective solution.



FEATURE

- Data rates scalable from 2.5GT/s to 32GT/s to support system upgrades without costly redesigns.
- Reference differential impedance: 85Ω
- Optional connector form factors 50pin/64pin/70pin/80pin

BENEFIT

- Meets PCI Express industry specification.
- Minimizes impedance discontinuities
- Meet customer different applications

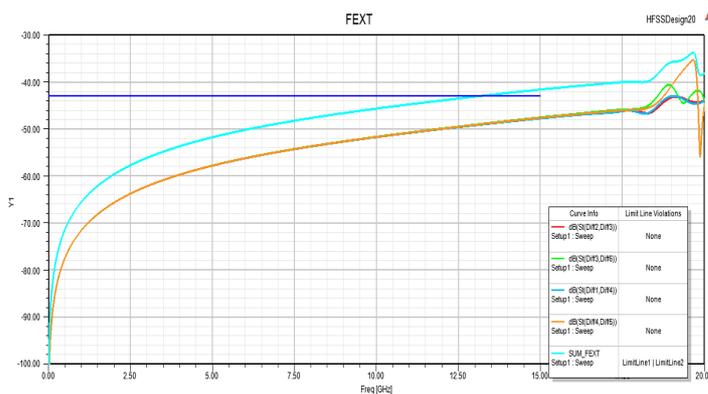
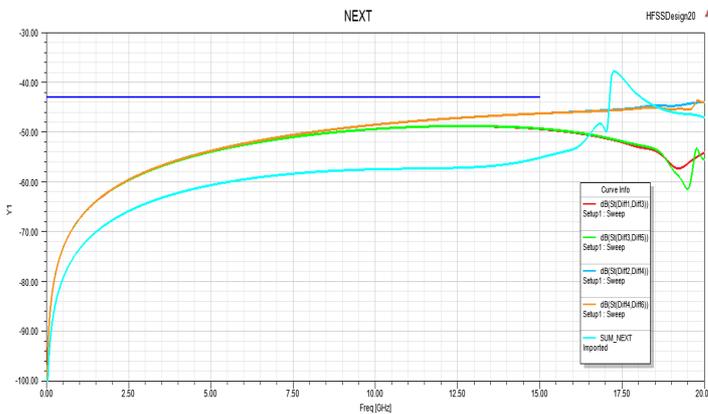
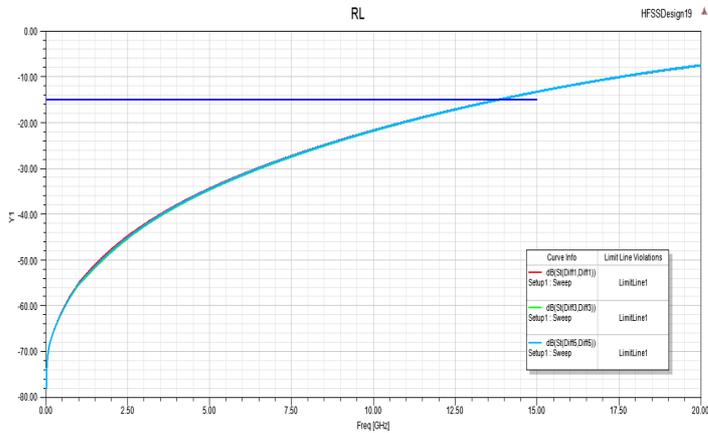
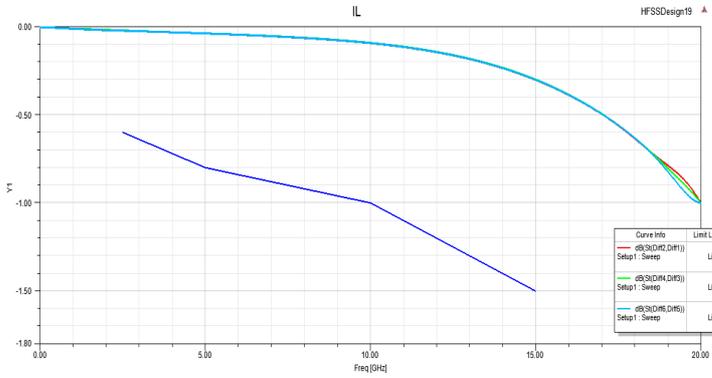
TARGET MARKET

- Desk Top



TECHNICAL INFORMATION

SIGNAL INTEGRITY PERFORMANCE



MECHANICAL PERFORMANCE

- Insertion force (module to connector): 1.92kgf/Pair max.
- Unmating force: 1.92kgf/Pair min.
- Terminal retention force: 50gf min.
- Durability: 20cycles.

ELECTRICAL PERFORMANCE

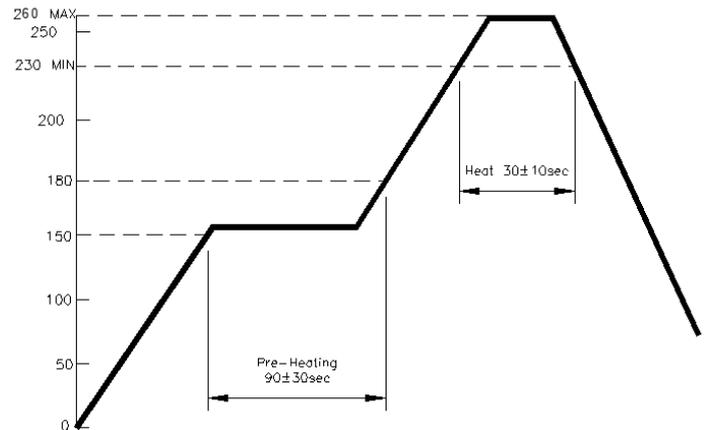
- Low level contact resistance: 20mΩ initial, Δ20mΩ
- Insulation resistance: 500MΩ min.
- Dielectric withstanding voltage: 500VAC.
- Current rating: 0.2A/pin De-rate

ENVIRONMENTAL

- Flammability: UL 94 V-0
- Low halogen: 1000ppm max. Cl, 1000ppm max Br.
- Compliant with RoHS directive 2011/65/EU
- Operating Temperature: -20° C to +85° C

APPLICATION SPEC

- Wave solder peak temperature: Max. 260° C , 10S
- Reflow temperature profile:



- Recommended SMT stencil thickness: 0.08mm